ABBOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Compo © Copyright 2005. IP international and Pan-	sition De C, Bannock American c	claration burn, Illinois. A opyright conver	ll rights reserved u ntions.	nder both	This docume level parts, t	ent is a decla he declaratio	aration of on encom	f the substa npasses all	inces wi lower le	thin the manufactur evel materials for wl	er listed it hich the m	em. Note: anufactur	: if the item is an as er has engineering	ssembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information				
Supplier Information															
Company name*			Company unique ID			Unique ID Authority					Response Date*				
onsemi											2024-05-04				
Contact Name	Title - Contac	Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date Version		ersion	Ma	Manufacturing Site		Veight*	UOM	Unit Type	
	NCV42	94CSN50T1G	5V/30mA LDO			2024-05-04	1		МУ	MY1		4.15	mg	Each	
Manufacturing Proccess Informat	ion								•	-	k		I	I	
Terminal Plating / Grid Array Mat	erial	Ferminal Base A	Alloy J	J-STD-020 MSL R		Peak Process Body Te		Body Tempo	erature Max Time at Peak T		Temperat	Temperature Number of Reflow Cycles		cles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		L		260		C		30	secon	is 3			
Comments						•		·			•	·			
vel 1 - maximum time at peak temperatu	e during so	Idering is 10-3	0 seconds												
or more information regarding material o															

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ohthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.87	mg	Supplier	Silicon (Si)	7440-21-3		0.87	mg
Die Attach	0.11	mg		Epoxy resin	proprietary data		0.033	mg
			Supplier	Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin	68475-94-5		0.033	mg
			Supplier	2,2'-[[2-(oxiranylmethoxy)-1,3- phenylene]bis(methylene)]bisoxirane	13561-08-5		0.033	mg
			Supplier	4-Methyl-2-Phenyl-1H-Imidazole	827-43-0		0.0099	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0011	mg
Lead Frame	5.72	mg	Supplier	Zinc (Zn)	7440-66-6		0.0057	mg
			Supplier	Iron (Fe)	7439-89-6		0.1316	mg
			Supplier	Copper (Cu)	7440-50-8		5.577	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0057	mg
Mold Compound-Black	7.34	mg		Epoxy resin	proprietary data		0.5505	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1835	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.5505	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0367	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.0188	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0017	mg
			В	Nickel (Ni)	7440-02-0		0.0616	mg
			Supplier	Gold (Au)	7440-57-5		0.0067	mg
Wire Bond - Au	0.04	mg	Supplier	Gold (Au)	7440-57-5		0.04	mg